



Material Content Data Sheet



Sales Product Name		BSS138W H6327		Issued		1. August 2018			
MA#		MA001233752							
Package		PG-SOT323-3-2		Weight*		6.17 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.002	0.03		335		
	noble metal	gold	7440-57-5	0.008	0.13		1300		
	inorganic material	silicon	7440-21-3	0.091	1.47	1.63	14733	16368	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86		
	non noble metal	titanium	7440-32-6	0.003	0.04		431		
	non noble metal	chromium	7440-47-3	0.008	0.13		1293		
	non noble metal	copper	7440-50-8	2.647	42.92	43.10	429207	431017	
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	872	872	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.50		4950		
	plastics	epoxy resin	-	0.656	10.64		106434		
	inorganic material	silicondioxide	60676-86-0	2.366	38.37	49.51	383658	495042	
leadfinish	non noble metal	tin	7440-31-5	0.133	2.15	2.15	21516	21516	
plating	noble metal	silver	7440-22-4	0.217	3.52	3.52	35185	35185	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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